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**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**

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Sheet 1

of 1

Complete if Known

Application Number	10/816,168
Filing Date	April 2, 2004
First Named Inventor	Tsutomu NAKADA
Group Art Unit	
Examiner Name	
Attorney Docket Number	NAKATA3

U.S. PATENT DOCUMENTS					
Examiner Initials*	Cite No. ¹	Document Number Number-Kind Code ² (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
/EW/	AA	US-6,350,366	02-26-2002	LANDAU, et al	
		US-			
		US-			
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FOREIGN PATENT DOCUMENTS						
Examiner Initials*	Cite No. ¹	Foreign Patent Number Country Code ³ Number ⁴ Kind Code ⁵ (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T ⁶
/EW/	AB	JP11-05871	09-12-2000	KURIHARA MIKA		

OTHER PRIOR ART - NON PATENT LITERATURE DOCUMENTS					
Examiner Initials*	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published			T ²
/EW/	AC	MANABU TSUJIMURA et al "A Novel Compact ECD Tool for ULSI Cu Metalization", The Ninth International Symposium on Semiconductor Manufacturing, pp: 106-109 no date			

Examiner Signature	/Edna Wong/	Date Considered	01/22/2008
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